

1. General description

Planar passivated very sensitive gate four quadrant triac in a SOT82 (SIP3) plastic package intended for use in general purpose bidirectional switching and phase control applications, where high sensitivity is required in all four quadrants. This "series D" triac is intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

2. Features and benefits

- High blocking voltage capability
- Planar passivated for voltage ruggedness and reliability
- Very sensitive gate
- Triggering in all four quadrants
- Direct interfacing to logic level ICs
- Direct interfacing to low power gate drive circuits
- Low holding current for low current loads and lowest EMI at commutation
- Compact package

3. Applications

- General purpose low power motor control
- Home appliances
- Industrial process control

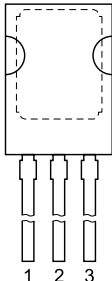

4. Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Values | | | Unit |
|--------------------------------|--------------------------------------|--|--------|-----|-----|------|
| Absolute maximum rating | | | | | | |
| V_{DRM} | repetitive peak off-state voltage | | 600 | | | V |
| $I_{T(RMS)}$ | RMS on-state current | full sine wave; $T_{mb} \leq 107\text{ °C}$; Fig. 1 ; Fig. 2 ; Fig. 3 | 4 | | | A |
| I_{TSM} | non-repetitive peak on-state current | full sine wave; $T_{j(initial)} = 25\text{ °C}$; $t_p = 20\text{ ms}$; Fig. 4 ; Fig. 5 | 25 | | | A |
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
| Static characteristics | | | | | | |
| I_{GT} | gate trigger current | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G+; $T_j = 25\text{ °C}$; Fig. 7 | - | 2 | 5 | mA |
| | | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G-; $T_j = 25\text{ °C}$; Fig. 7 | - | 2.5 | 5 | mA |
| | | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G-; $T_j = 25\text{ °C}$; Fig. 7 | - | 2.5 | 5 | mA |
| | | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G+; $T_j = 25\text{ °C}$; Fig. 7 | - | 5 | 10 | mA |
| I_H | holding current | $V_D = 12\text{ V}$; $T_j = 25\text{ °C}$; Fig. 9 | - | 1.2 | 10 | mA |

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|--------------------------------|---|---|
| 1 | T1 | main terminal 1 |  |  |
| 2 | T2 | main terminal 2 | | |
| 3 | G | gate | | |
| mb | T2 | mounting base; main terminal 2 | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-------------|---------|---|---------|
| | Name | Description | Version |
| BT134-600D | SIP3 | plastic single-ended package; 3-leads (in-line) | SOT82 |

7. Marking

Table 4. Marking codes

| Type number | Marking codes |
|-------------|---------------|
| BT134-600D | BT134-600D |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Values | Unit |
|--------------|--------------------------------------|---|------------|-------------|
| V_{DRM} | repetitive peak off-state voltage | | 600 | V |
| $I_{T(RMS)}$ | RMS on-state current | full sine wave; $T_{mb} \leq 107\text{ °C}$; Fig 1 ; Fig 2 ; Fig 3 | 4 | A |
| I_{TSM} | non-repetitive peak on-state current | full sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 20\text{ ms}$; Fig 4 ; Fig 5 | 25 | A |
| | | full sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 16.7\text{ ms}$ | 27 | A |
| I^2t | I^2t for fusing | $t_p = 10\text{ ms}$; SIN | 3.1 | A^2s |
| di_T/dt | rate of rise of on-state current | $I_G = 20\text{ mA}$; T2+ G+ | 50 | $A/\mu s$ |
| | | $I_G = 20\text{ mA}$; T2+ G- | 50 | $A/\mu s$ |
| | | $I_G = 20\text{ mA}$; T2- G- | 50 | $A/\mu s$ |
| | | $I_G = 20\text{ mA}$; T2- G+ | 10 | $A/\mu s$ |
| I_{GM} | peak gate current | | 2 | A |
| P_{GM} | peak gate power | | 5 | W |
| $P_{G(AV)}$ | average gate power | over any 20 ms period | 0.5 | W |
| T_{stg} | storage temperature | | -40 to 150 | $^{\circ}C$ |
| T_j | junction temperature | | 125 | $^{\circ}C$ |

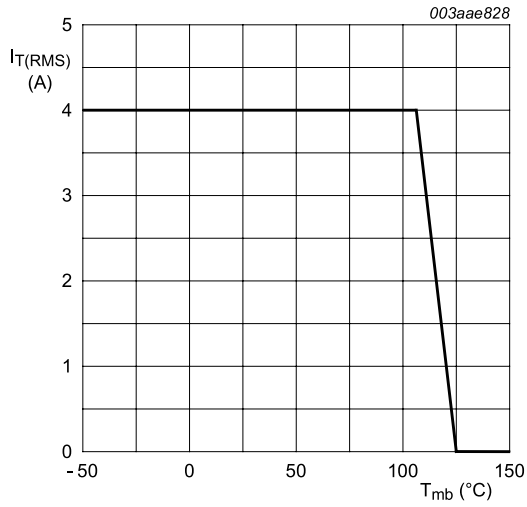
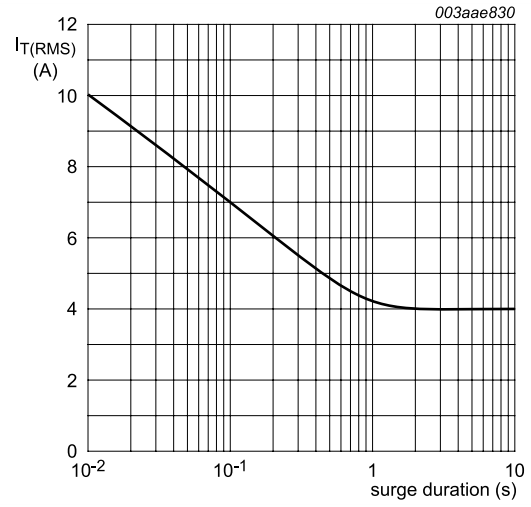


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



f = 50 Hz; T_{mb} ≤ 107 °C

Fig. 2. RMS on-state current as a function of surge duration; maximum values

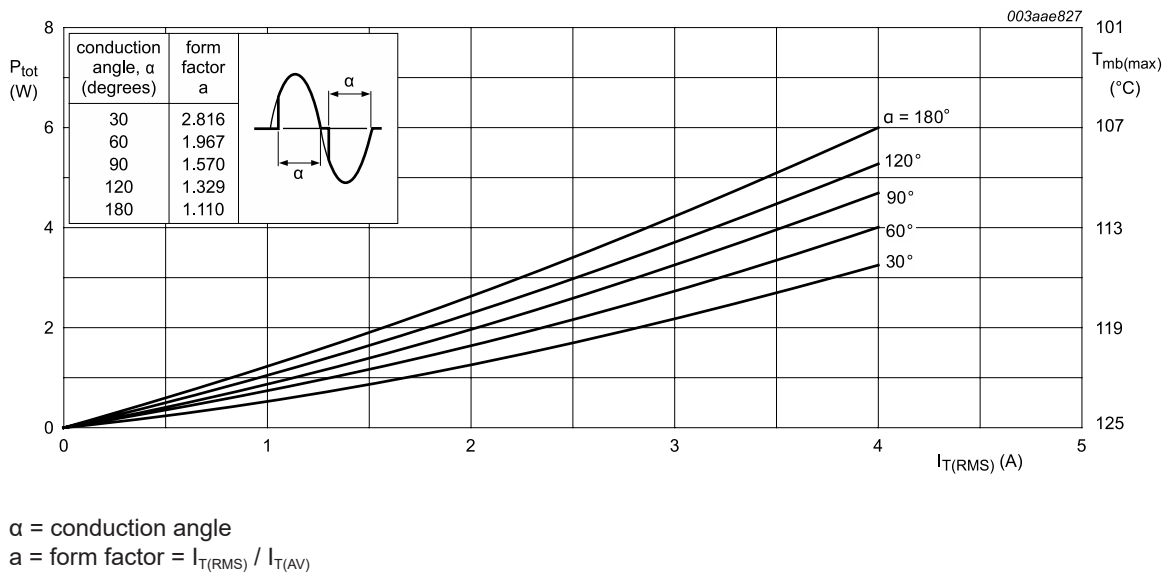


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

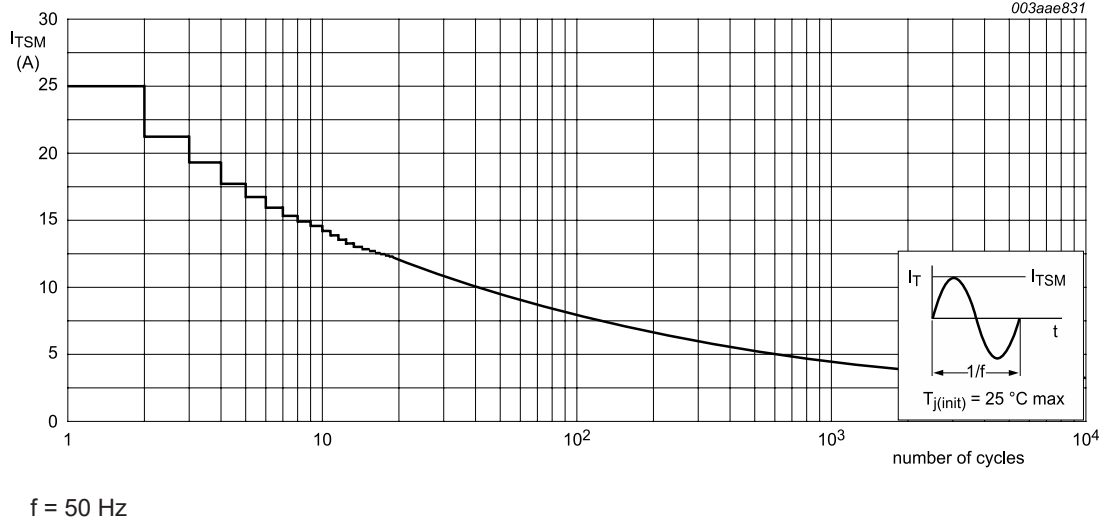


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

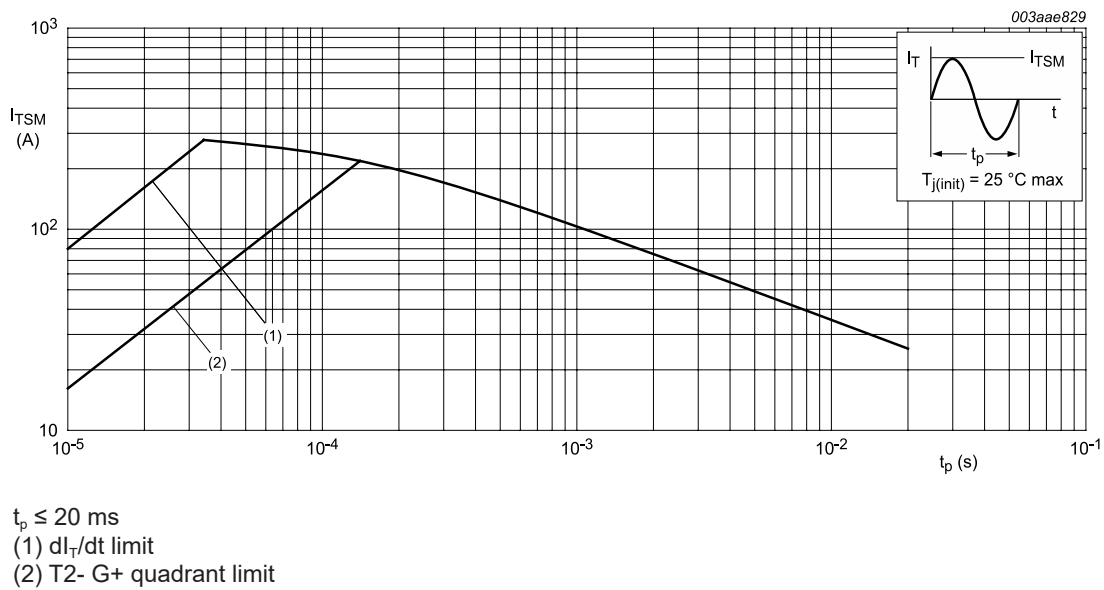


Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|---|-------------------|-----|-----|-----|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | half cycle; Fig 6 | - | - | 3.7 | K/W |
| | | full cycle; Fig 6 | - | - | 3 | K/W |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | - | 100 | - | K/W |

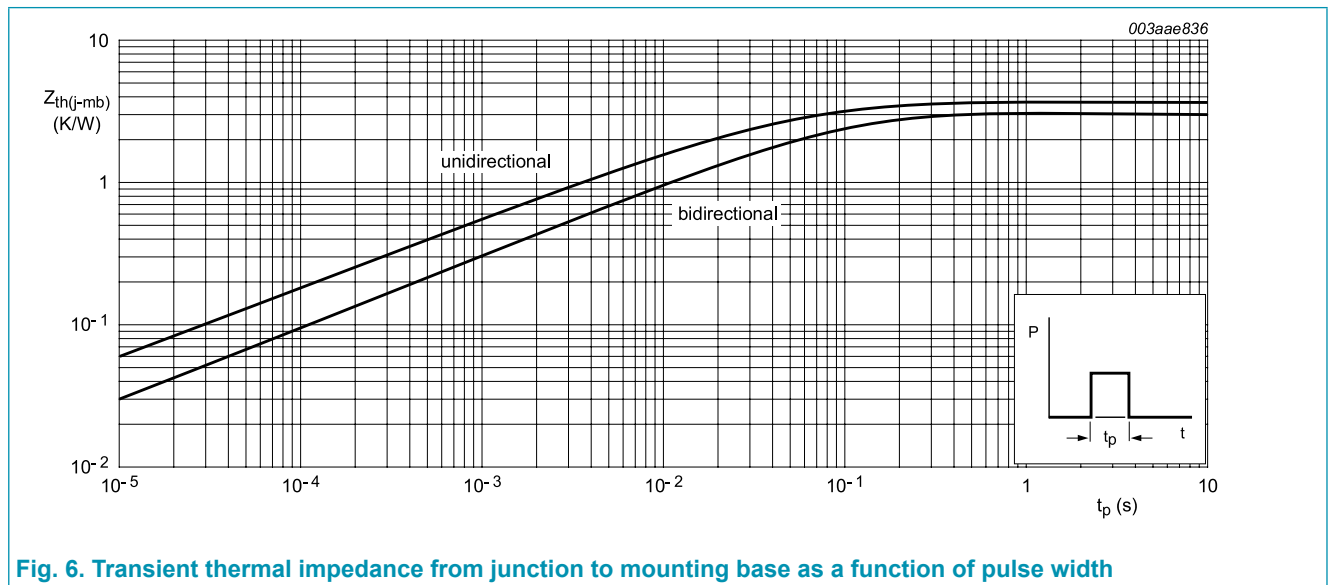
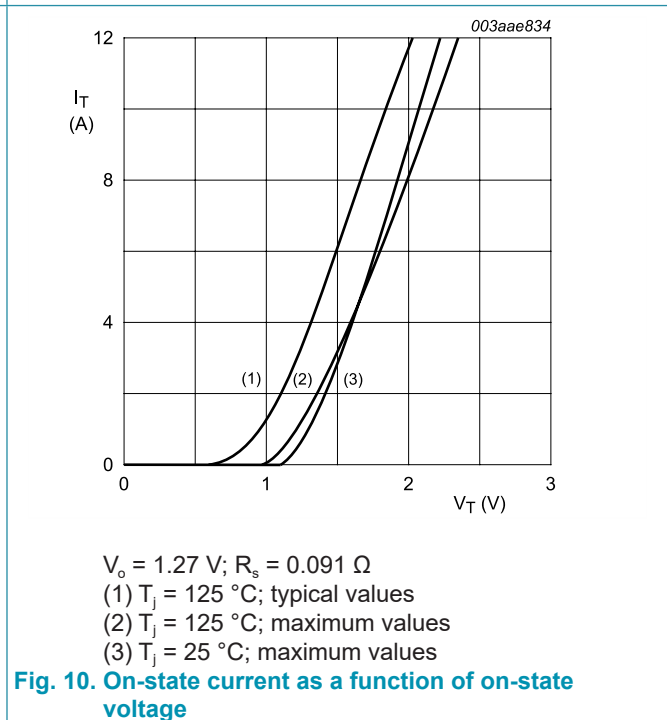
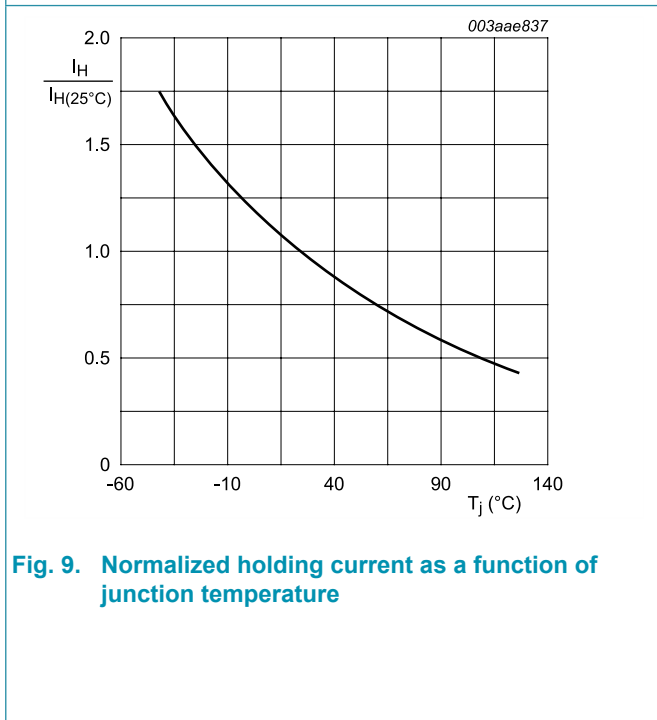
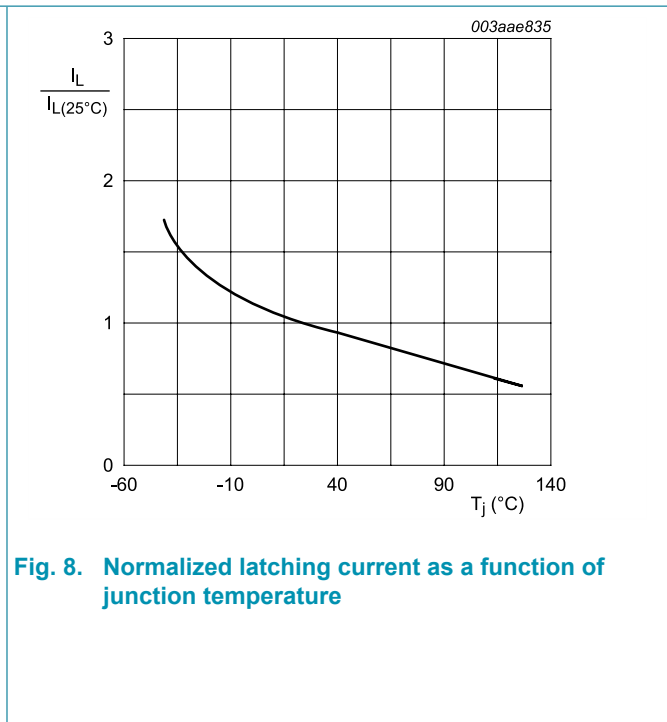
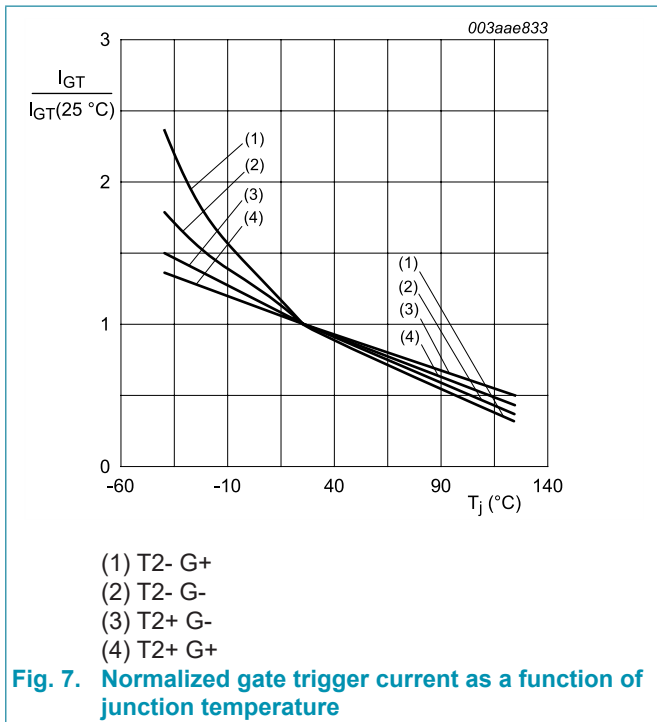


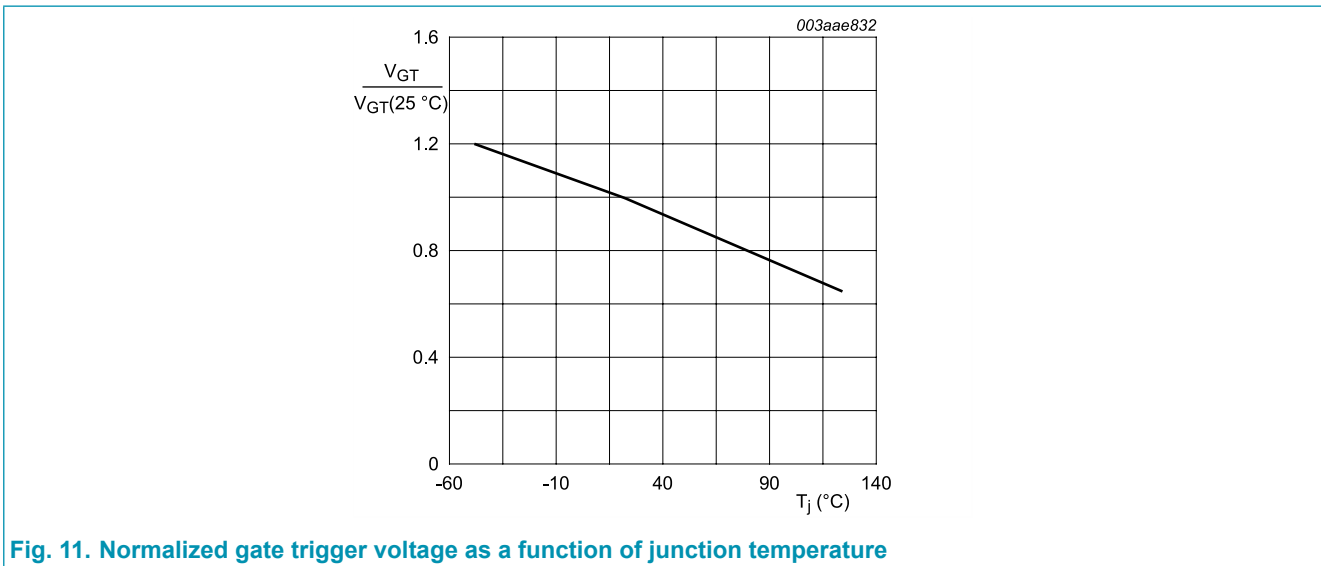
Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse width

10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|-----------------------------------|--|------|-----|-----|------------------|
| Static characteristics | | | | | | |
| I_{GT} | gate trigger current | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G+; $T_j = 25\text{ °C}$; Fig. 7 | - | 2 | 5 | mA |
| | | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G-; $T_j = 25\text{ °C}$; Fig. 7 | - | 2.5 | 5 | mA |
| | | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G-; $T_j = 25\text{ °C}$; Fig. 7 | - | 2.5 | 5 | mA |
| | | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G+; $T_j = 25\text{ °C}$; Fig. 7 | - | 5 | 10 | mA |
| I_L | latching current | $V_D = 12\text{ V}$; $I_G = 0.1\text{ A}$; T2+ G+; $T_j = 25\text{ °C}$; Fig. 8 | - | 1.6 | 10 | mA |
| | | $V_D = 12\text{ V}$; $I_G = 0.1\text{ A}$; T2+ G-; $T_j = 25\text{ °C}$; Fig. 8 | - | 4.5 | 15 | mA |
| | | $V_D = 12\text{ V}$; $I_G = 0.1\text{ A}$; T2- G-; $T_j = 25\text{ °C}$; Fig. 8 | - | 1.2 | 10 | mA |
| | | $V_D = 12\text{ V}$; $I_G = 0.1\text{ A}$; T2- G+; $T_j = 25\text{ °C}$; Fig. 8 | - | 2.2 | 15 | mA |
| I_H | holding current | $V_D = 12\text{ V}$; $T_j = 25\text{ °C}$; Fig. 9 | - | 1.2 | 10 | mA |
| V_T | on-state voltage | $I_T = 5\text{ A}$; $T_j = 25\text{ °C}$; Fig. 10 | - | 1.4 | 1.7 | V |
| V_{GT} | gate trigger voltage | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 11 | - | 0.7 | 1 | V |
| | | $V_D = 400\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 125\text{ °C}$; Fig. 11 | 0.25 | 0.4 | - | V |
| I_D | off-state current | $V_D = 600\text{ V}$; $T_j = 125\text{ °C}$ | - | 0.1 | 0.5 | mA |
| Dynamic characteristics | | | | | | |
| dV_D/dt | rate of rise of off-state voltage | $V_{DM} = 402\text{ V}$; $T_j = 125\text{ °C}$; $R_{GT1} = 1\text{ k}\Omega$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform | - | 5 | - | V/ μs |
| t_{gt} | gate-controlled turn-on time | $V_D = 600\text{ V}$; $I_{TM} = 6\text{ A}$; $I_G = 0.1\text{ A}$; $di_G/dt = 5\text{ A}/\mu\text{s}$ | - | 2 | - | μs |

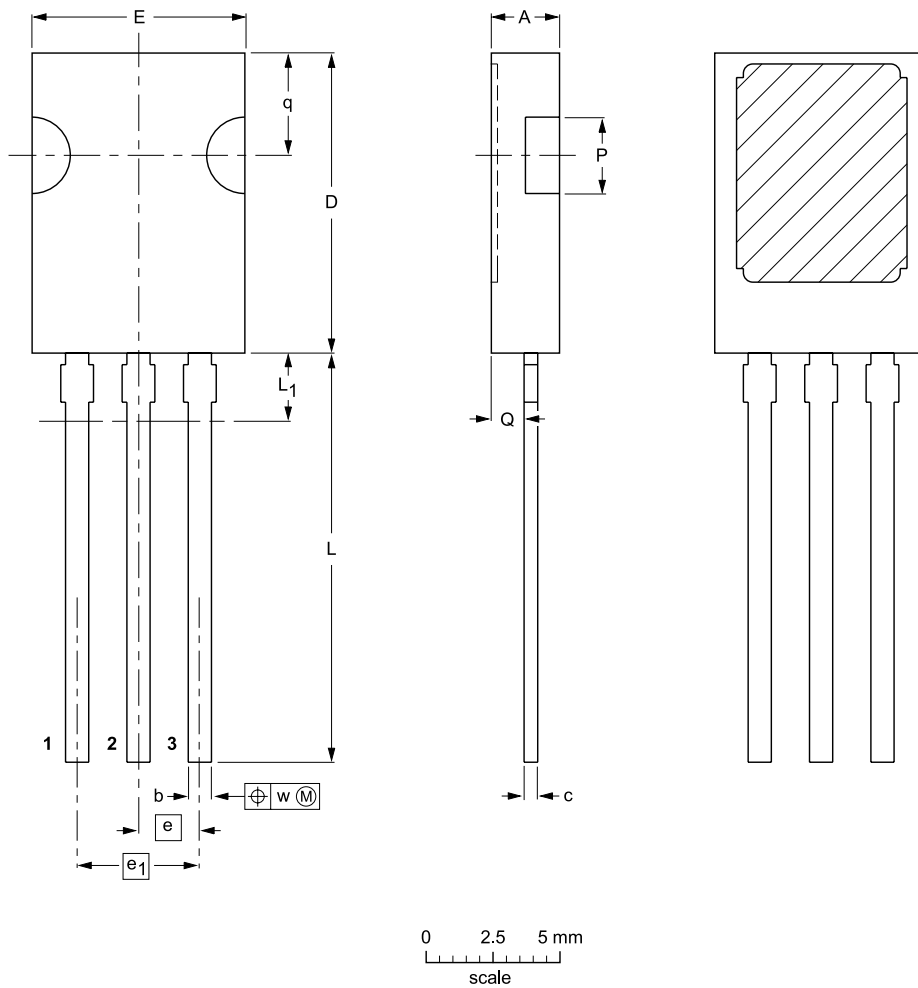




11. Package outline

Plastic single-ended package; 3 leads (in-line)

SOT82



DIMENSIONS (mm are the original dimensions)

| UNIT | A | b | c | D | E | e | e ₁ | L | L ₁ ⁽¹⁾ max. | P | Q | q | w |
|------|------------|--------------|--------------|--------------|------------|------|----------------|--------------|---------------------------------------|------------|------------|------------|-------|
| mm | 2.8 2.3 | 0.88 0.65 | 0.58 0.47 | 11.1 10.5 | 7.8 7.2 | 2.29 | 4.58 | 16.5 15.3 | 2.54 | 3.1 2.5 | 1.5 0.9 | 3.9 3.5 | 0.254 |

Note

1. Terminal dimensions within this zone are uncontrolled to allow for body and terminal irregularities.

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|-------|------|--|---------------------|------------|
| | IEC | JEDEC | EIAJ | | | |
| SOT82 | | | | | | 97-06-11 |

12. Legal information

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|--------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
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13. Contents

| | |
|----------------------------------|----|
| 1. General description..... | 1 |
| 2. Features and benefits | 1 |
| 3. Applications | 1 |
| 4. Quick reference data | 1 |
| 5. Pinning information..... | 2 |
| 6. Ordering information..... | 2 |
| 7. Marking..... | 2 |
| 8. Limiting values | 3 |
| 9. Thermal characteristics | 6 |
| 10. Characteristics..... | 7 |
| 11. Package outline | 10 |
| 12. Legal information | 11 |
| 13. Contents | 13 |

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